



### 800V N-Channel Power MOSFET

**TO-220** 

**ITO-220** 



Pin Definition:

- Gate
  Drain
- 3. Source

#### PRODUCT SUMMARY

V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)
800	1.05 @ V <sub>GS</sub> =10V	9.5

### **General Description**

The TSM10N80 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

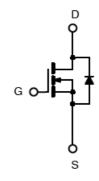
#### **Features**

- Low R<sub>DS(ON)</sub> 1.05Ω (Max.)
- Low gate charge typical @ 53nC (Typ.)
- Improve dv/dt capability

### **Ordering Information**

Part No.	Package	Packing		
TSM10N80CZ C0	TO-220	50pcs / Tube		
TSM10N80CI C0	ITO-220	50pc / Tube		

### **Block Diagram**



N-Channel MOSFET

### **Absolute Maximum Rating** (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	800	V
Gate-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current	I <sub>D</sub>	9.5	А
Pulsed Drain Current *	I <sub>DM</sub>	38	А
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	267	mJ
Avalanche Current (Repetitive) (Note 1)	I <sub>AR</sub>	9.5	А
Repetitive Avalanche Energy (Note 1)	E <sub>AR</sub>	29	mJ
Operating Junction Temperature	TJ	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

<sup>\*</sup> Limited by maximum junction temperature







#### **Thermal Performance**

Parameter		Symbol	Limit	Unit
Thermal Resistance - Junction to Case	TO-220	DO.	0.43	°C/W
	ITO-220	Rθ <sub>JC</sub>	2.6	
Thermal Resistance - Junction to Ambient	TO-220 / ITO-220	$R\Theta_{JA}$	62.5	

Notes: Surface mounted on FR4 board t ≤ 10sec

### **Electrical Specifications** (Tc = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250uA$	BV <sub>DSS</sub>	800			V
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 4.75A$	R <sub>DS(ON)</sub>		0.9	1.05	Ω
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250uA$	V <sub>GS(TH)</sub>	2.0		4.0	V
Zero Gate Voltage Drain Current	$V_{DS} = 800V, V_{GS} = 0V$	I <sub>DSS</sub>			10	uA
Gate Body Leakage	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	I <sub>GSS</sub>			±100	nA
Forward Transconductance	$V_{DS} = 30V, I_{D} = 4.75A$	<b>g</b> fs		6.3		S
Diode Forward Voltage	$I_S = 9.5A, V_{GS} = 0V$	$V_{SD}$			1.5	V
Dynamic <sup>b</sup>				_		
Total Gate Charge	V <sub>DS</sub> = 640V, I <sub>D</sub> = 9.5A,	$Q_g$		53		
Gate-Source Charge		$Q_gs$		10		nC
Gate-Drain Charge	$V_{GS} = 10V$	$Q_gd$		23		
Input Capacitance	\/ OF\/ \/ O\/	C <sub>iss</sub>		2336		
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$	$C_{oss}$		214		pF
Reverse Transfer Capacitance	f = 1.0MHz	$C_{rss}$		29		
Switching <sup>c</sup>				_		
Turn-On Delay Time		t <sub>d(on)</sub>		63		
Turn-On Rise Time	$V_{GS} = 10V, I_D = 9.5A,$ $V_{DD} = 400V, R_G = 25\Omega$	t <sub>r</sub>		62		0
Turn-Off Delay Time		$t_{d(off)}$		256		nS
Turn-Off Fall Time		t <sub>f</sub>		72		
Reverse Recovery Time	$V_{GS} = 0V, I_S = 9.5A,$	t <sub>fr</sub>		450		nS
Reverse Recovery Charge	$dI_F/dt = 100A/us$	$Q_{fr}$		5.3		uC

### Notes:

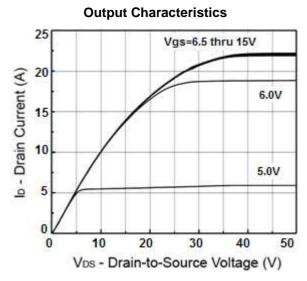
- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- 2.  $V_{DD} = 50V$ ,  $I_{AS}=10A$ , L=5mH,  $R_G=25\Omega$
- 3.  $I_{SD} \le 9.5A$ , di/dt  $\le 200A/uS$ , Vdd  $\le BV$
- 4. Pulse test: pulse width ≤300uS, duty cycle ≤2%
- 5. b For design reference only, not subject to production testing.
- 6. c Switching time is essentially independent of operating temperature.



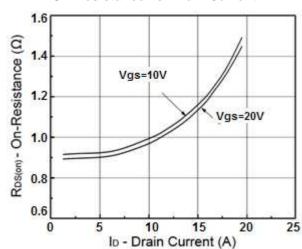
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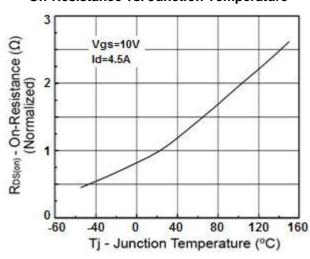
### **Electrical Characteristics Curve** (Tc = 25°C, unless otherwise noted)



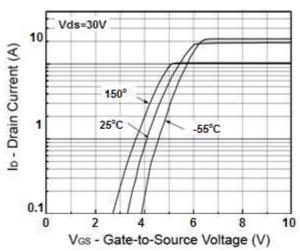
#### **On-Resistance vs. Drain Current**



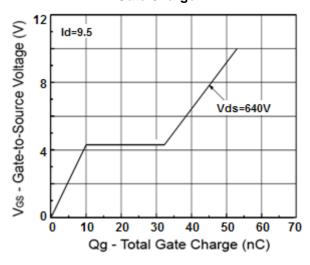
### On-Resistance vs. Junction Temperature



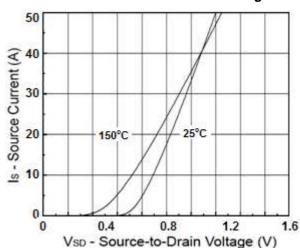
#### **Transfer Characteristics**



#### **Gate Charge**



#### Source-Drain Diode Forward Voltage





### 800V N-Channel Power MOSFET

BV<sub>DSS</sub> vs. Junction Temperature

Vgs=0V

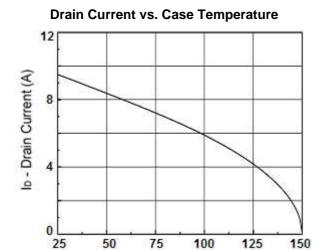
-40

0.8

-60



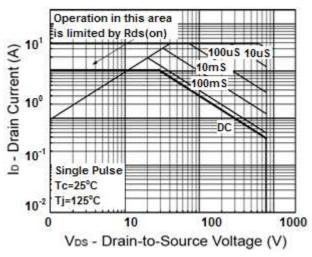
### Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)



BVpss - Drain-Source Breakdown Voltage (V) (Normalized) Id=250uA

#### **Maximum Safe Operating Area**

Tc - Case Temperature (°C)



Capacitance vs. Drain-Source Voltage

40

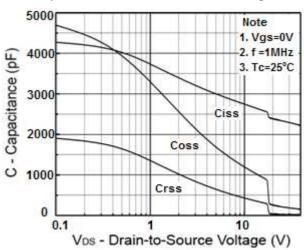
Tj - Junction Temperature (°C)

80

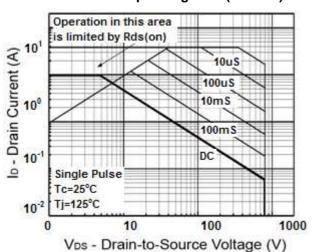
120

160

0



#### **Maximum Safe Operating Area (ITO-220)**



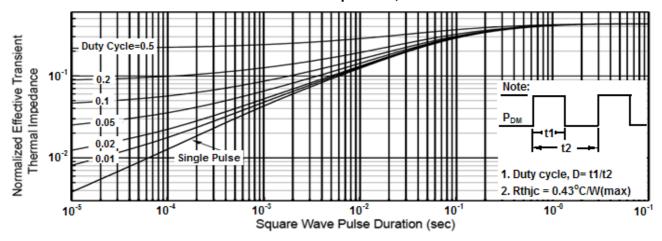




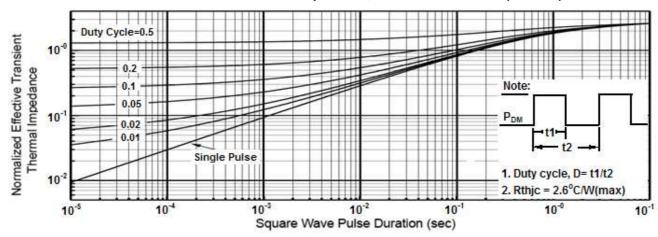


### Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)

#### Normalized Thermal Transient Impedance, Junction-to-Ambient



#### Normalized Thermal Transient Impedance, Junction-to-Ambient(ITO-220)

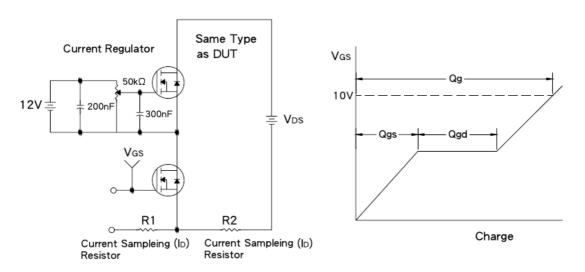




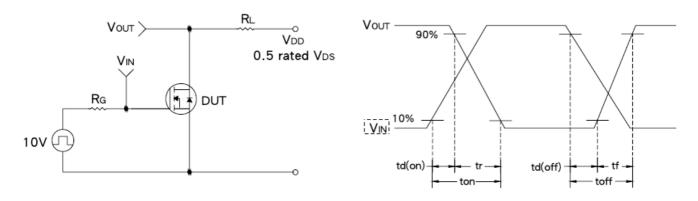
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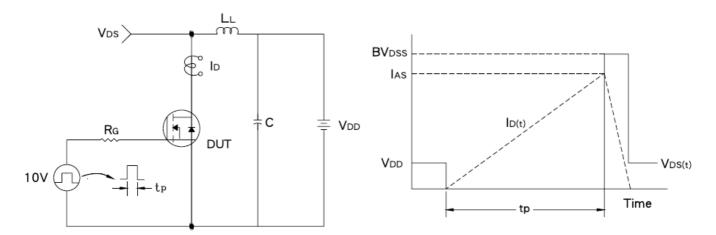
### **Gate Charge Test Circuit & Waveform**



### **Resistive Switching Test Circuit & Waveform**



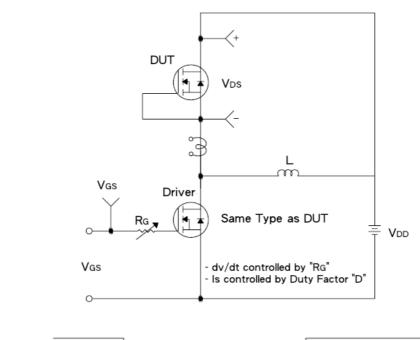
### **EAS Test Circuit & Waveform**

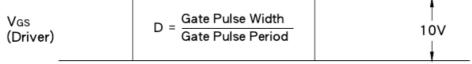


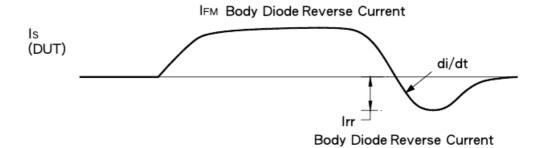
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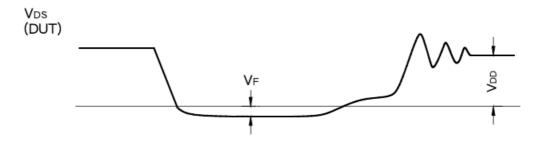


### **Diode Reverse Recovery Time Test Circuit & Waveform**







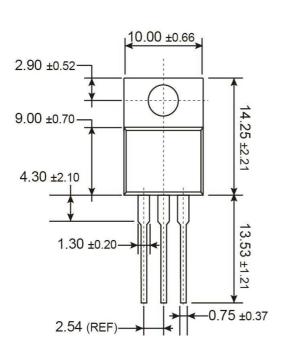


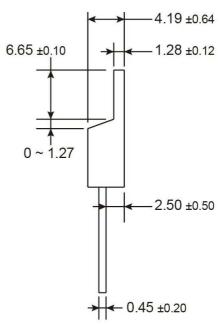


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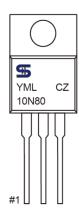
### **TO-220 Mechanical Drawing**





Unit: Millimeters

### **Marking Diagram**



Y = Year Code

M = Month Code

(A=Jan, B=Feb, C=Mar, D=Apl, E=May, F=Jun, G=Jul, H=Aug,

I=Sep, J=Oct, K=Nov, L=Dec)

L = Lot Code

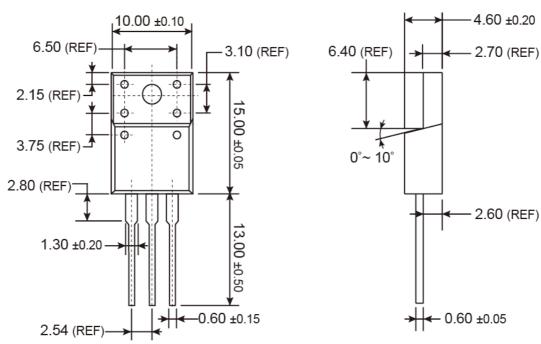




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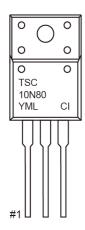


### **ITO-220 Mechanical Drawing**



Unit: Millimeters

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